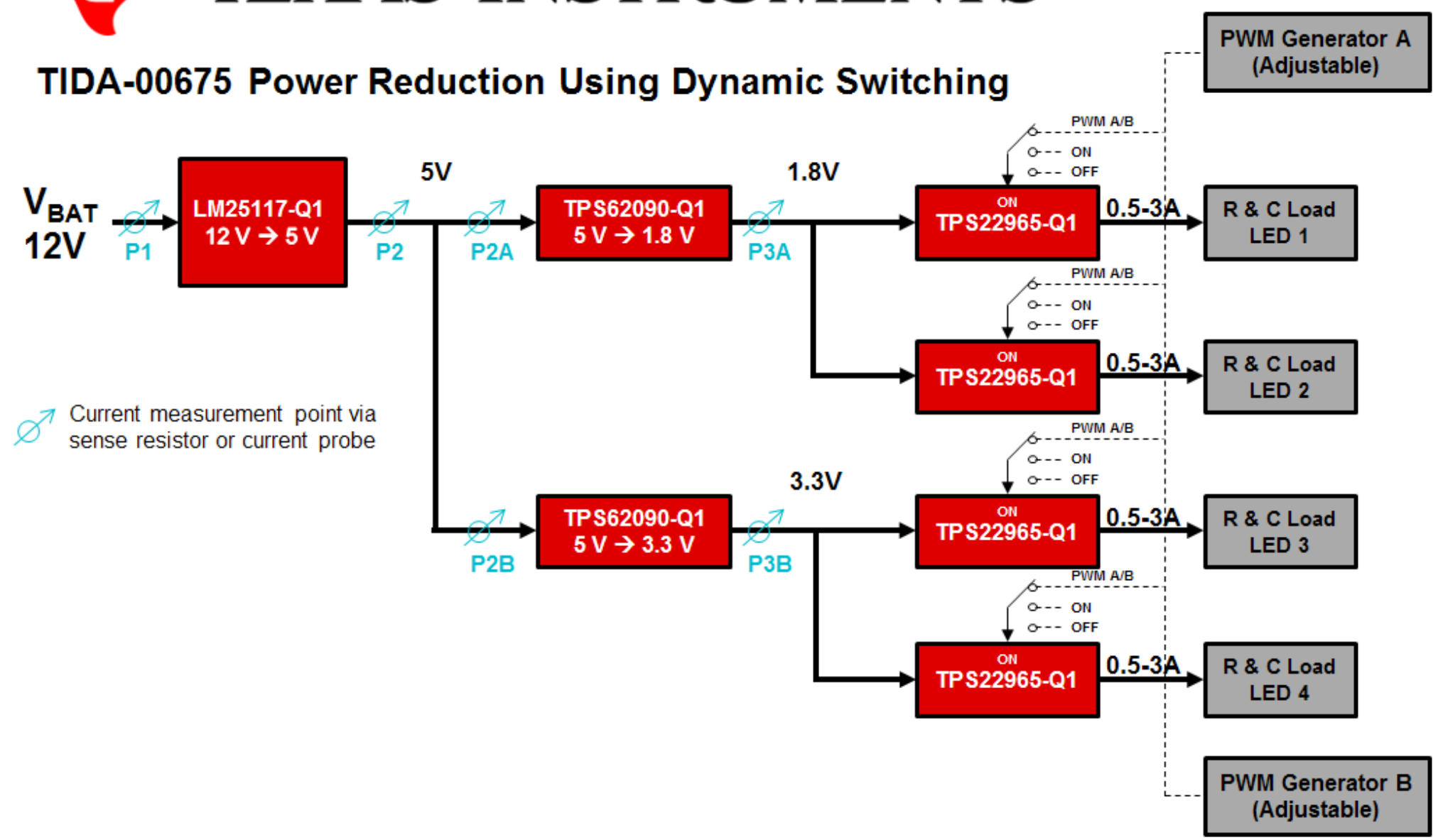


Revision History				
Rev	ECN #	Approved Date	Approved by	Notes
N/A	N/A	N/A	N/A	N/A



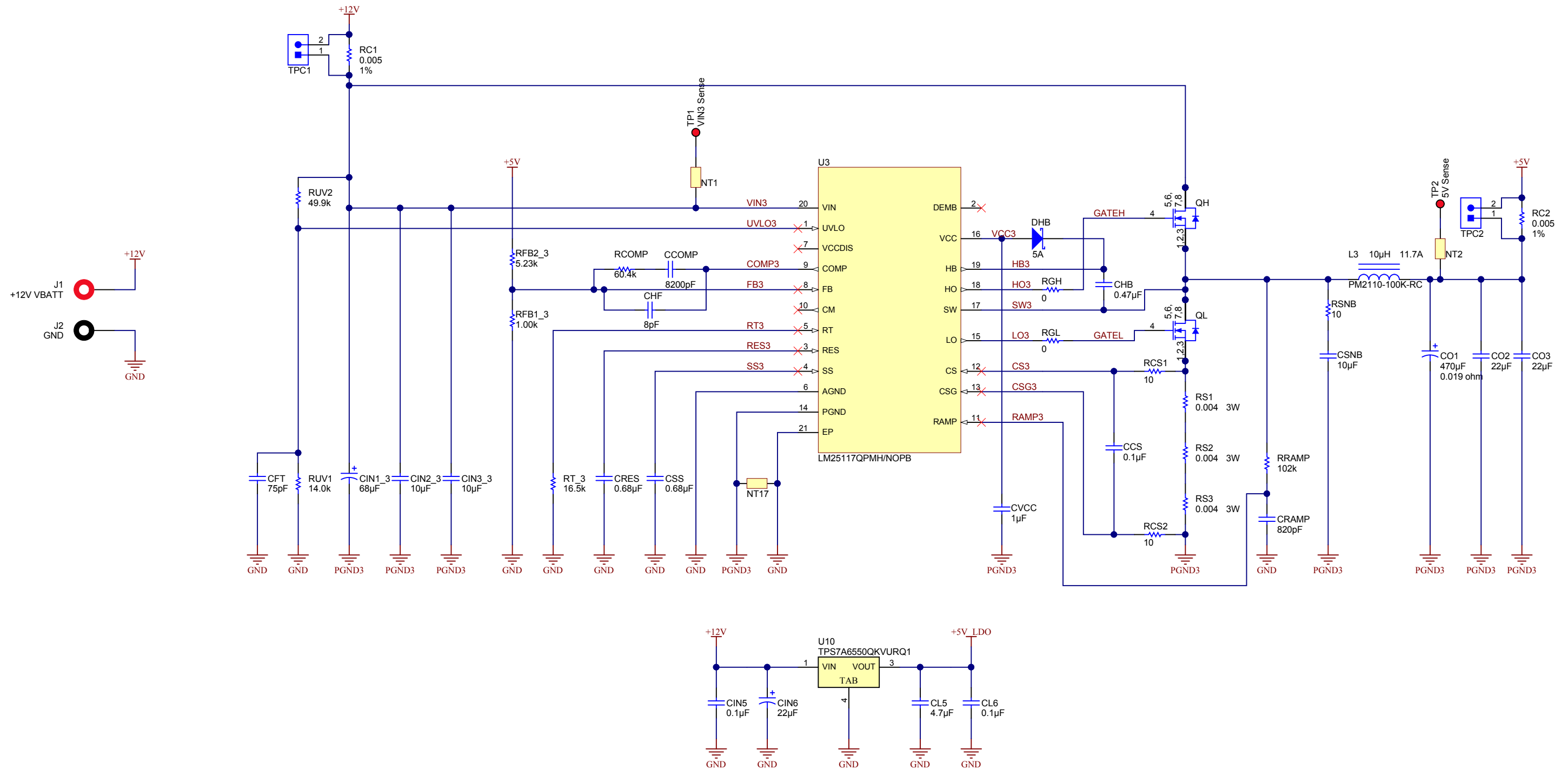
## TIDA-00675 Power Reduction Using Dynamic Switching



Current measurement point via sense resistor or current probe

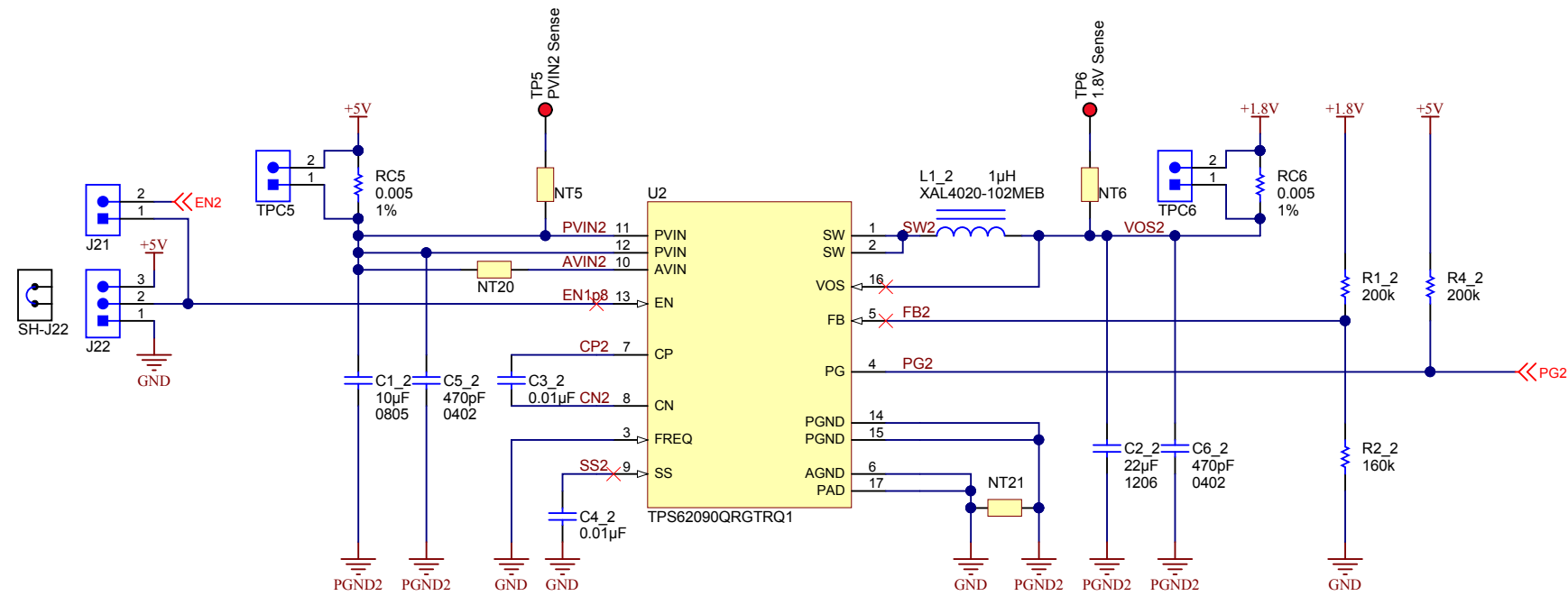
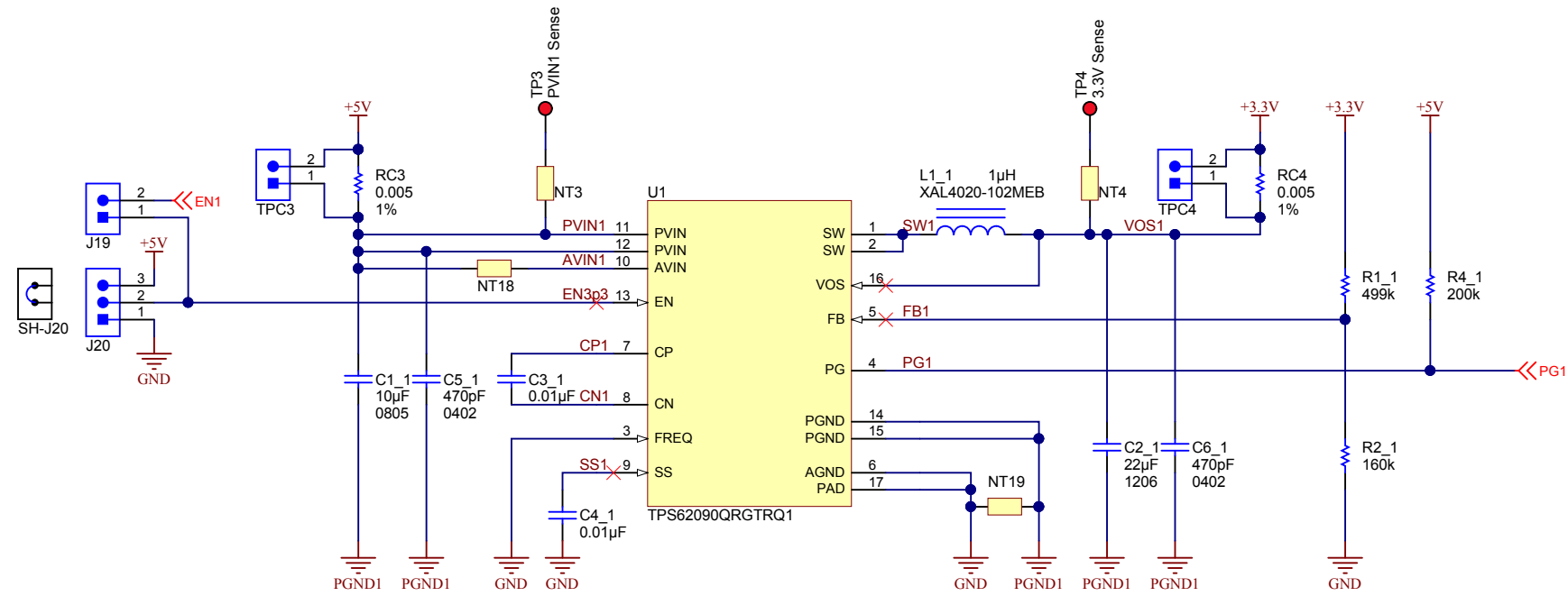
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TID #: TIDA-00675	Project Title: Power Reduction using Dynamic Switching		
Number: TIDA-00675	Rev: E1	Sheet Title:	
SVN Rev: Version control disabled	Assembly Variant: [No Variations]		
Drawn By:	File: CoverSheet.SchDoc	Sheet: 1 of 7	
Engineer: Brian Lackey	Contact: <a href="http://www.ti.com/support">http://www.ti.com/support</a>	Size: B	

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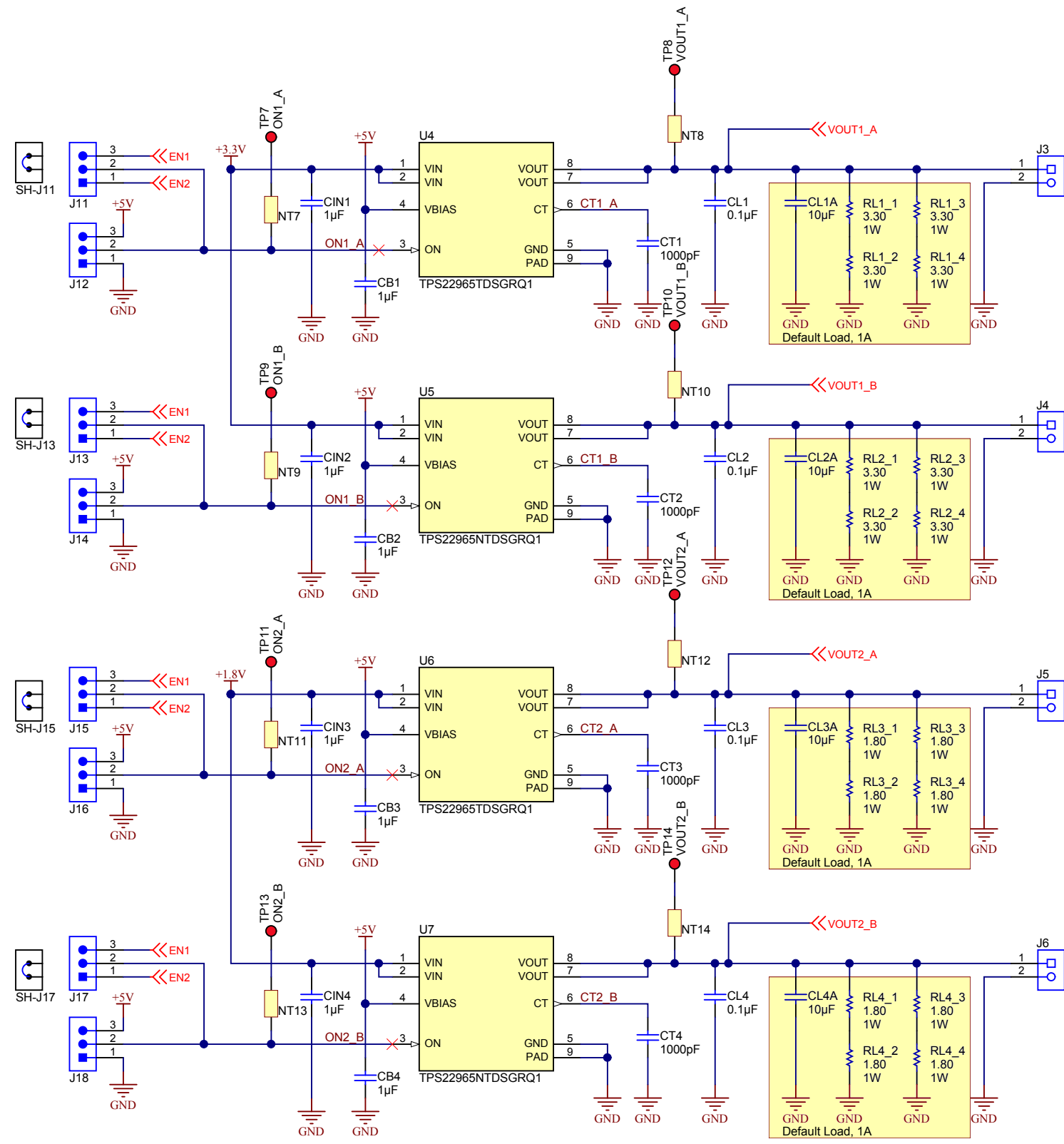
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TID #: TIDA-00675	Project Title: Power Reduction using Dynamic Switching	Sheet: 2 of 7	
Number: TIDA-00675	Rev: E1	File: Input Regulation_SchDoc	Size: B
SVN Rev: Version control disabled	Assembly Variant: [No Variations]	Engineer: Brian Lackey	Contact: <a href="http://www.ti.com/support">http://www.ti.com/support</a>



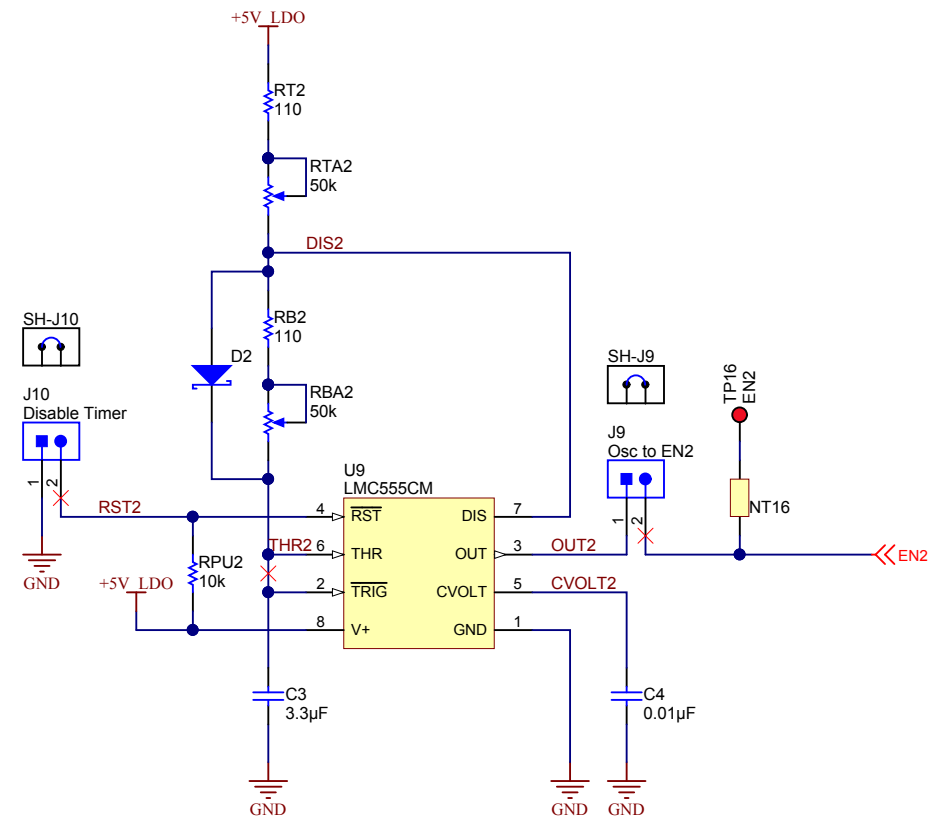
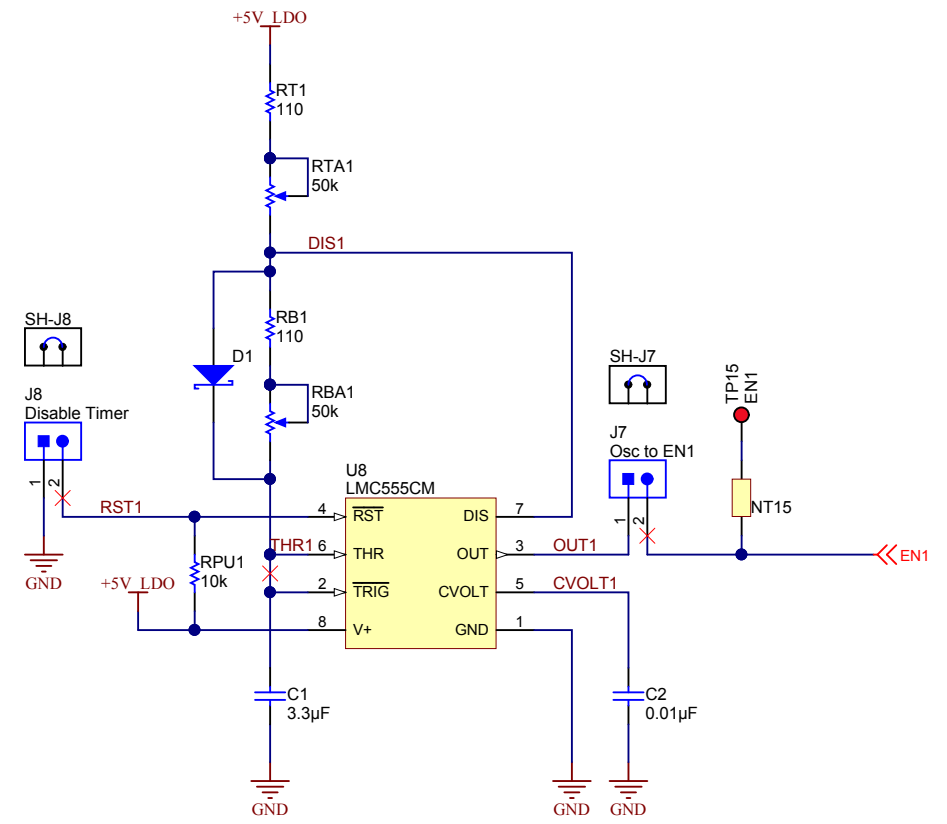
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Number: TIDA-00675	Rev: E1	Assembly Variant: [No Variations]	Sheet: 3 of 7
SVN Rev: Version control disabled	File: Output Regulation.SchDoc	Size: B	http://www.ti.com
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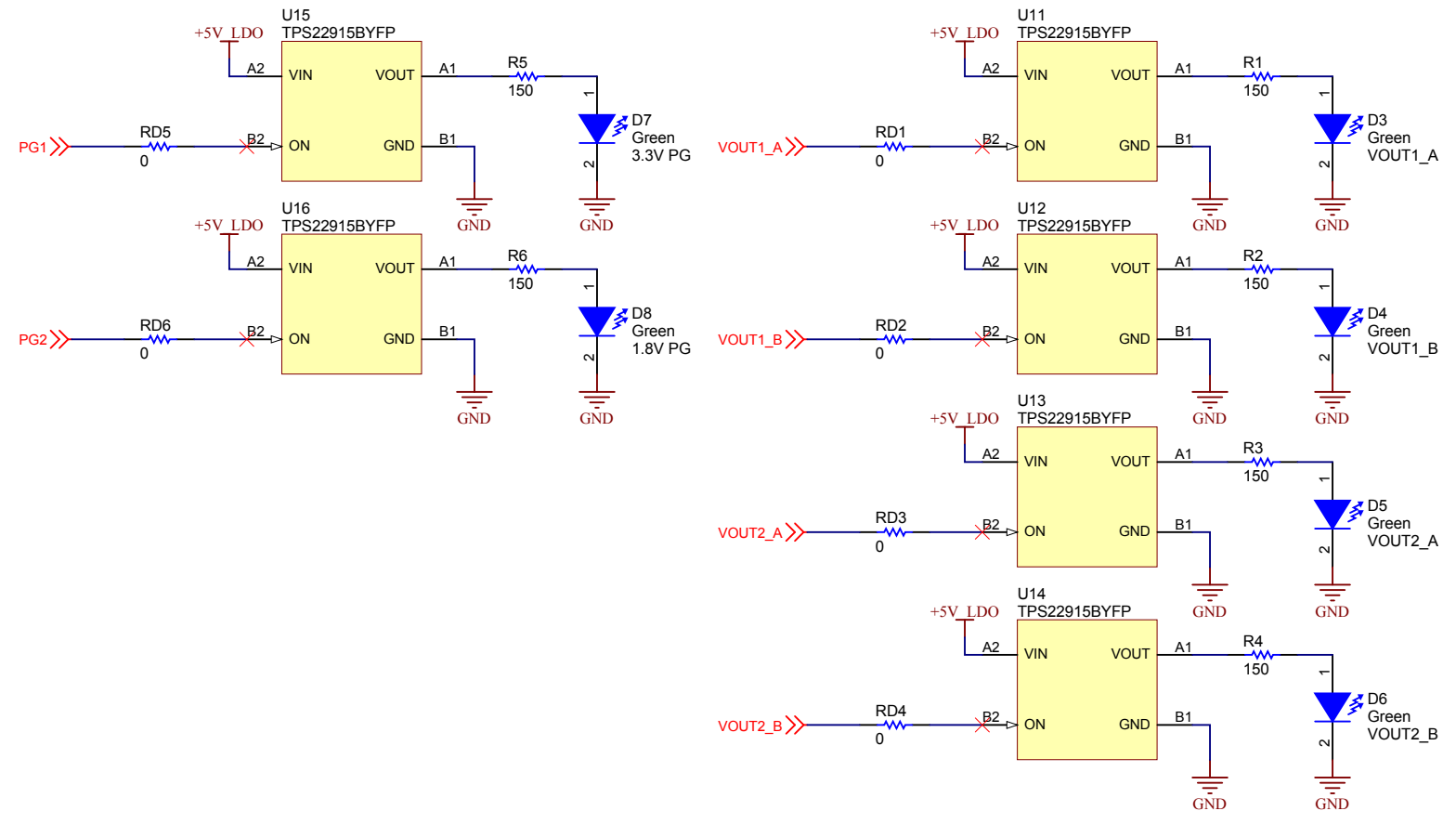
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Number: TIDA-00675	Rev: E1	Sheet Title:
SVN Rev: Version control disabled	Assembly Variant: [No Variations]	Sheet: 5 of 7
Drawn By:	File: Oscillators.SchDoc	Size: B
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Number: TIDA-00675	Rev: E1	Assembly Variant: [No Variations]	Sheet: 6 of 7
SVN Rev: Version control disabled	File: Diagnostics.SchDoc	Size: B	http://www.ti.com
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H1 SJ-5303 (CLEAR) H2 SJ-5303 (CLEAR) H3 SJ-5303 (CLEAR) H4 SJ-5303 (CLEAR)

FID1 FID2 FID3 FID4 FID5 FID6

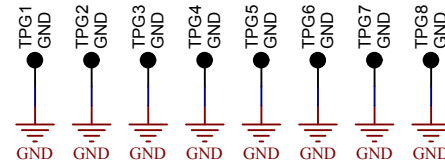
PCB Number: TIDA-00675  
PCB Rev: E1

PCB  
LOGO  
Texas Instruments

PCB  
LOGO  
Pb-Free Symbol

EDGE 6592767

Label Table	
Variant	Label Text
001	Default Configuration




ZZ2  
**Assembly Note**  
These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3  
**Assembly Note**  
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4  
**Assembly Note**  
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

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TID #: TIDA-00675	Project Title: Power Reduction using Dynamic Switching	Sheet: 7 of 7	
Number: TIDA-00675	Rev: E1	File: TID_Hardware.SchDoc	Size: B
SVN Rev: Version control disabled	Engineer: Brian Lackey	Contact: <a href="http://www.ti.com/support">http://www.ti.com/support</a>	© Texas Instruments 2015

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